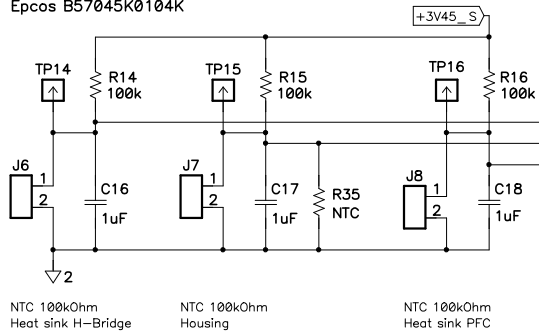


Notes

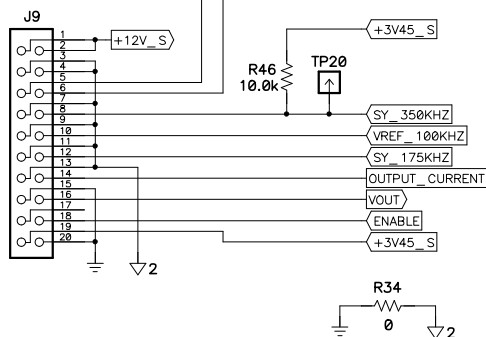
- \* Place C101 (1nF) directly on U2 (no footprint available)
- \* Frame for LCD: Electronic Assembly EA 017-2 UKE
- \* Built on PCB "PMP5568 - 350W PSU - MCU Card RevB.pcb"

Connectors for external NTCs  
Epcos B57045K0104K



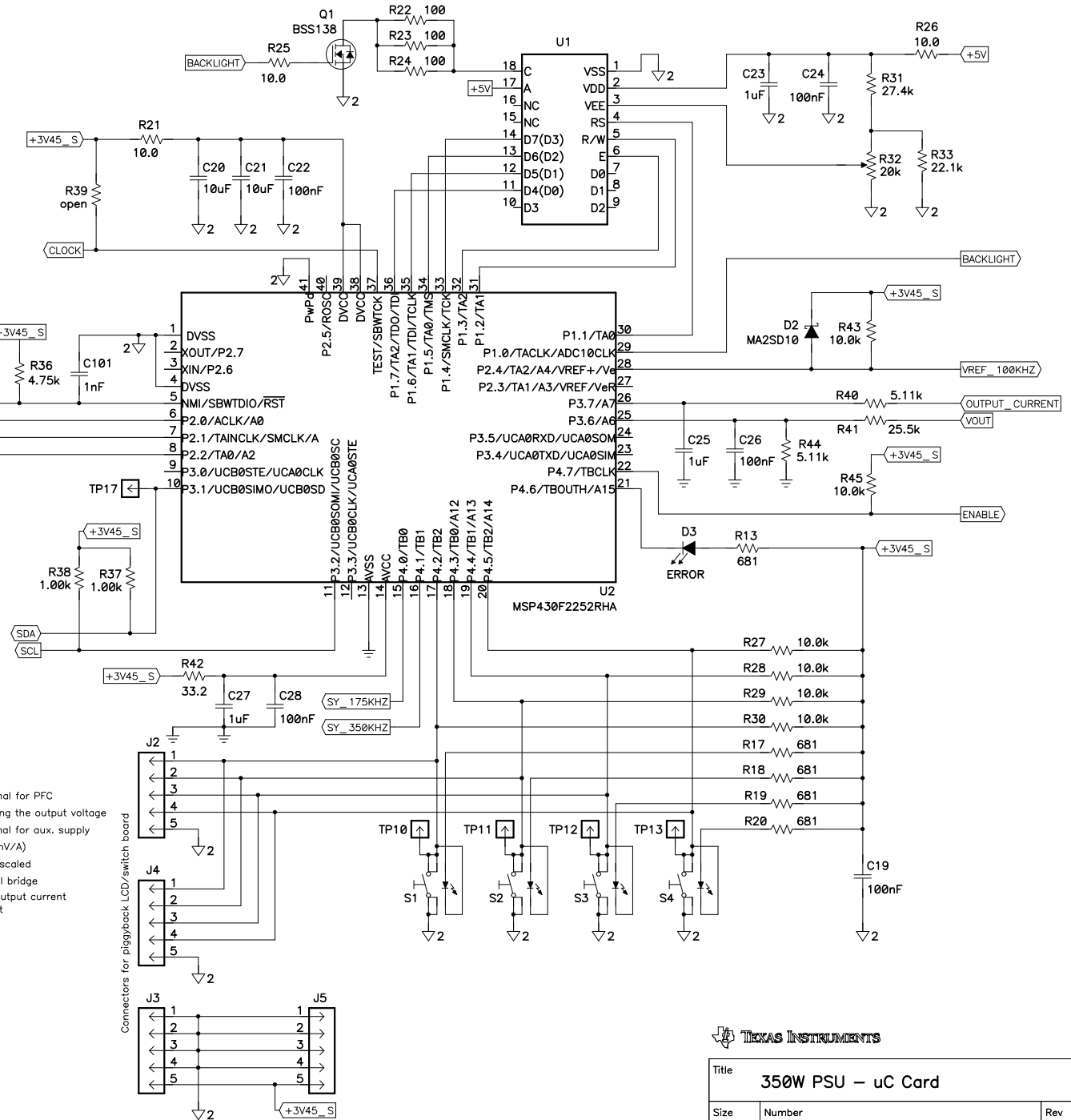
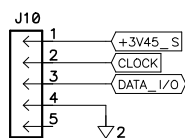
NTC 100kOhm Heat sink H-Bridge  
NTC 100kOhm Housing  
NTC 100kOhm Heat sink PFC

Power Board Connector



Synchronization signal for PFC  
PWM signal for setting the output voltage  
Synchronization signal for aux. supply  
Output current (33mV/A)  
Output voltage, not scaled  
Enable signal for full bridge  
Supply voltage for output current measurement circuit

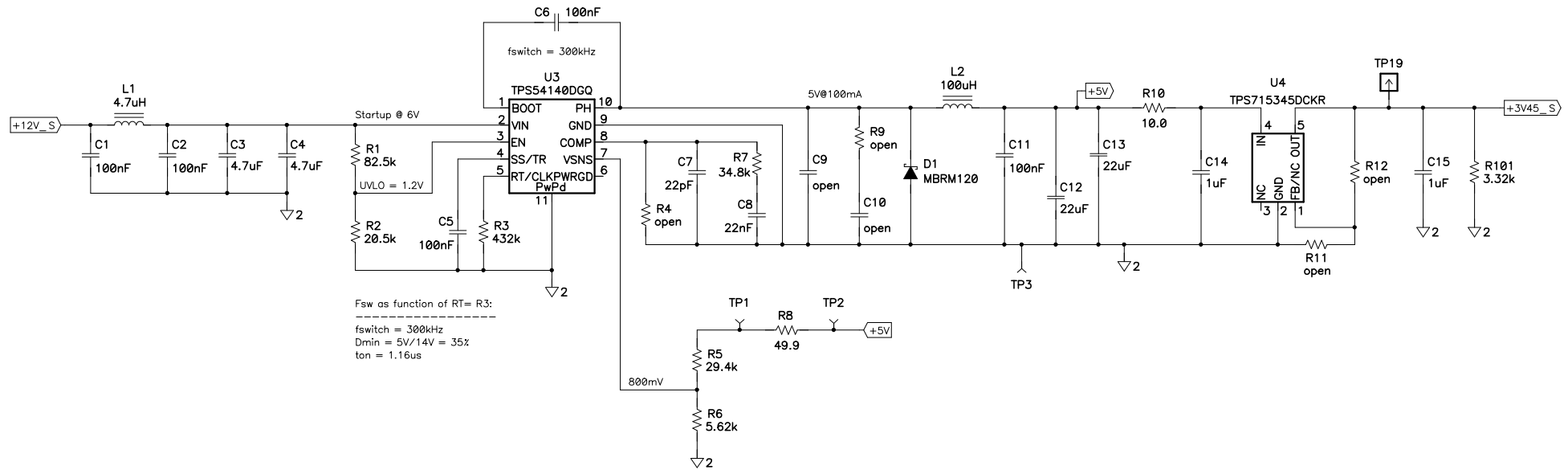
2-Wire JTAG interface  
(Spy-Bi-Wire)



Title <b>350W PSU - uC Card</b>		
Size <b>C</b>	Number <b>PMP5568</b>	Rev <b>D</b>
Date 5/16/2011	Drawn by M. Marjanovic	
Filename PMP5568 - 350W PSU - MCU Card RevB.sch	Sheet 1	of 2

Notes

- \* R8 for test purpose only
- \* R101 placed piggyback on C15



Fsw as function of RT= R3:  
 -----  
 fswitch = 300kHz  
 Dmin = 5V/14V = 35%  
 ton = 1.16us



Title <b>350W PSU - uC Card</b>		
Size C	Number <b>PMP5568</b>	Rev D
Date 5/16/2011	Drawn by M. Marjanovic	
Filename PMP5568 - 350W PSU - MCU Card RevB.sch	Sheet 2	of 2

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